

Title (en)

COPPER ALLOY FOR ELECTRICAL/ELECTRONIC DEVICE AND METHOD FOR PRODUCING THE SAME

Title (de)

KUPFERLEGIERUNG FÜR ELEKTRISCHE/ELEKTRONISCHE VORRICHTUNG UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)

ALLIAGE DE CUIVRE POUR UN DISPOSITIF ÉLECTRIQUE/ÉLECTRONIQUE ET SON PROCÉDÉ DE FABRICATION

Publication

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Application

EP 08722882 A 20080326

Priority

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- JP 2007080266 A 20070326
- JP 2008079256 A 20080325

Abstract (en)

[origin: EP2143810A1] A copper alloy for an electrical and electronic device in accordance with the present invention is characterized in that the copper alloy for an electrical and electronic device includes: nickel (Ni) between 1.5 mass% and 5.0 mass%; silicon (Si) between 0.4 mass% and 1.5 mass%; and a remaining portion formed of Cu and an unavoidable impurity, wherein a mass ratio between Nickel (Ni) and Silicon (Si) as Ni/Si is not smaller than two and not larger than seven, an average crystalline grain diameter is not smaller than 2 µm and not larger than 20 µm, and a standard deviation of the crystalline grain diameter is not larger than 10 µm.

IPC 8 full level

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Citation (search report)

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